

The 7th International Conference
On Microelectronics and Plasma Technology

ICMAP 2018

Joint International Conference on
ICMAP 2018, APCPST 2018 and ISPB 2018

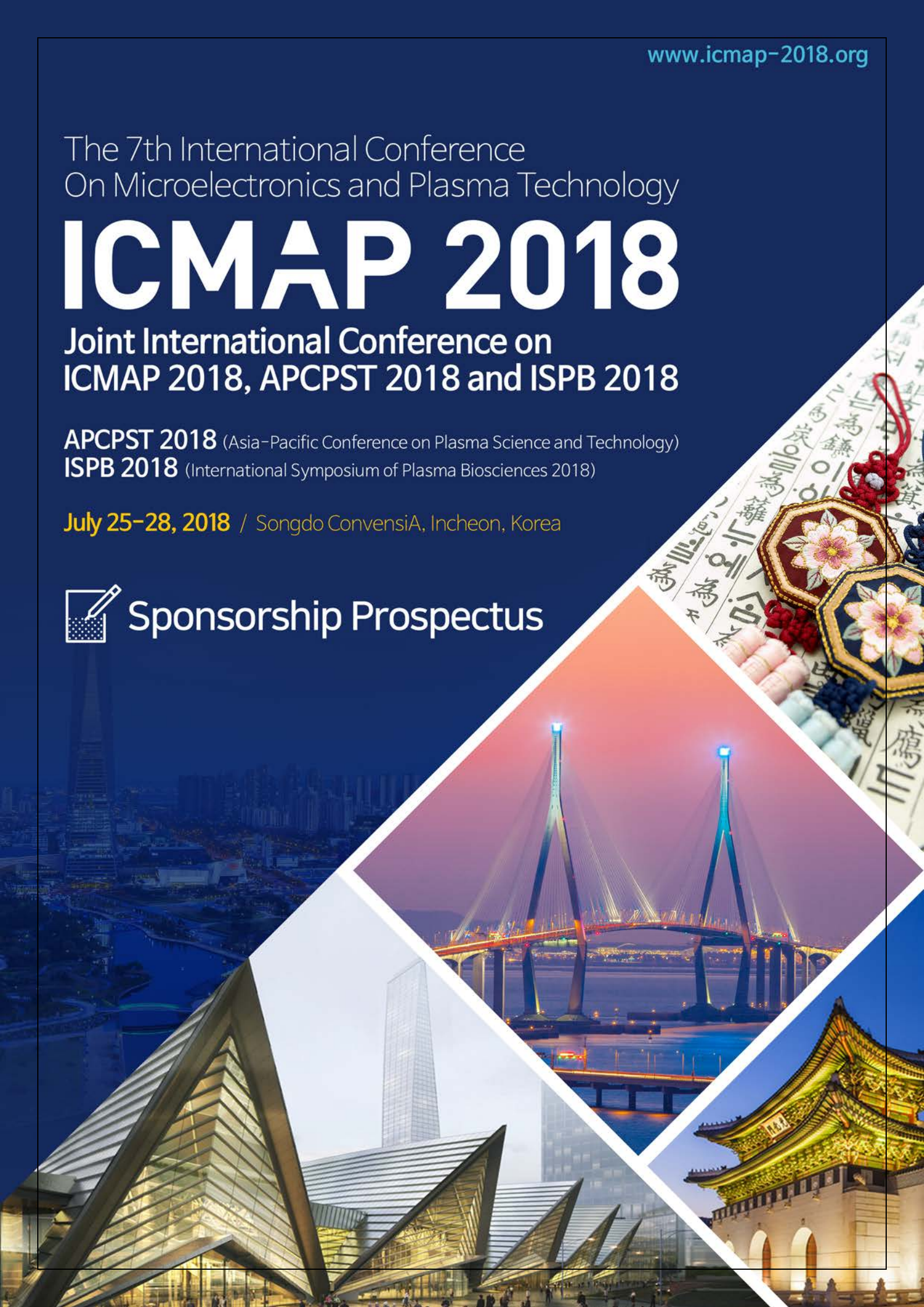
APCPST 2018 (Asia-Pacific Conference on Plasma Science and Technology)

ISPB 2018 (International Symposium of Plasma Biosciences 2018)

July 25-28, 2018 / Songdo ConvensiA, Incheon, Korea



Sponsorship Prospectus



ICMAP 2018

The 7th International Conference on Microelectronics and Plasma Technology

July 25–28, 2018 / Songdo ConvensiA, Incheon, Korea

Overview

Title	The 7th International Conference on Microelectronics and Plasma Technology (ICMAP 2018) Joint International conference on ICMAP 2018, APCPST 2018, and ISPB 2018 - APCPST 2018 (Asia-Pacific Conference on Plasma Science and Technology) - ISPB 2018 (International Symposium of Plasma Biosciences 2018)
Date	July 25 – 28, 2018
Venue	Songdo ConvensiA, Incheon, Korea
Attendees	300 Attendees
Organized by	The Korean Vacuum Society (KVS)
Sponsored by	The American Vacuum Society (AVS)

Organizing Committee

Honorary Chair	Chi Kyu Choi (Jeju Nat'l Univ., Korea)
Conference Chairs	Geun Young Yeom (Sungkyunkwan Univ., Korea) Suk Jae Yoo (Nat'l Fusion Research Inst., Korea) Eun Ha Choi (Kwangwoon Univ., Korea)
Int'l Organizing Chair	Hong Young Chang (KAIST, Korea)
Int'l Advisory Committee Chair	J. E. Greene (Univ. of Illinois at Urbana-Champaign)
Scientific Program Committee Chair	Jung Hoon Joo (Kunsan Nat'l Univ., Korea)
Publication Committee Chair	Nae-Eung Lee (Sungkyunkwan Univ., Korea)
General Secretaries	HeeHwan Choe (Korea Aerospace Univ., Korea) Shin Jae Yu (Chungnam Nat'l Univ., Korea) Deuk-Chul Kwon (Nat'l Fusion Research Inst., Korea) Hyo-Chang Lee (KRISS, Korea)

Programs

- Plenary Lectures
- Invited Session
- Oral Session
- Poster Session


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Sponsorship Information

[Sponsorship Package]

LEVEL	Platinum	Gold	Silver	Bronze
				
	KRW 20,000,000	KRW 10,000,000	KRW 5,000,000	KRW 3,000,000
Logo & Link on Homepage	O	O	O	O
Logo & Link on registration page	O	O	O	X
Advertising (Program Book)	1page color [Front cover] → <i>First come, first served</i>	1page color [Back cover] → <i>First come, first served</i>	1page color	1page black/white
Advertising (Abstract e-Book)	O	O	O	O
Logo on screen saver in session rooms	O	O	X	X
Free registration	18 Persons	8 Persons	3 Persons	1 Person
Logo on Conference site Information signage	O	O	O	O
Logo on the name badge	O	O	X	X
Logo on the name badge lanyard	O	X	X	X

※ The Sponsorship Packages are subject to change.

※ Please contact secretariat for further information.

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ICMAP 2018 Sponsorship Application Form

1. Registering company and person in charge

Company Name			
President / CEO			
Contact Person Name			
Department		Job Title	
Address	(Postal code:)		
Telephone		Fax	
E-mail			

2. Application

Check (V) for your choice	Category	Amount
	Platinum	KRW 20,000,000
	Gold	KRW 10,000,000
	Silver	KRW 5,000,000
	Bronze	KRW 3,000,000

3. Payment Method (Bank Transfer Only)

Account Holder	The Korean Vacuum Society
Bank Name	Citibank Korea Inc.
Account Number	163-01253-246-01
SWIFT Code	CITIKRSX
Bank Address	Haesung 2 Bldg. 942-10 Daechi-dong, Gangnam-gu, Seoul 135-725, Korea

Date: _____

Signature: _____

ICMAP 2018 Secretariat

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